

RZ/A2M Group

RZ/A2M CPG Driver

Introduction

This application note describes the operation of the software CPG Driver for the RZ/A2 device on the RZ/A2M CPU Board.

It provides a comprehensive overview of the driver. For further details please refer to the software driver itself.

The user is assumed to have knowledge of e² studio and to be equipped with an RZ/A2M CPU Board.

Target Device

RZ/A2M Group

Driver Dependencies

This driver depends on:

- Drivers
 - STDIO

Referenced Documents

Document Type	Document Name	Document No.
User's Manual	RZ/A2M Hardware Manual	R01UH0746EJ
Application Note	OS Abstraction Middleware	R11AN0309EG

List of Abbreviations and Acronyms

Abbreviation	Full Form
ANSI	American National Standards Institute
API	Application Programming Interface
ARM	Advanced RISC Machines
CPG	Clock Pulse Generator
CPU	Central Processing Unit
HLD	High Layer Driver
IDE	Integrated Development Environment
LLD	Low Layer Driver
OS	Operating System
PLL	Phase-Locked Loop
STDIO	Standard Input/Output

Table 1-1 List of Abbreviations and Acronyms

Contents

1. Outline of Software Driver	4
2. Description of the Software Driver	4
2.1 Structure	4
2.2 Description of each file.....	5
2.3 Driver API	6
3. Accessing the Driver.....	7
3.1 STDIO	7
3.2 Direct	7
3.3 Comparison	8
4. Example of Use.....	9
4.1 Open	9
4.2 Control – Set Crystal Frequency	9
4.3 Control – Set Main Clock.....	9
4.4 Control – Set Sub Clock	9
4.5 Control – Set Clock Source.....	9
4.6 Control – Set External Clock.....	9
4.7 Write	9
4.8 Read.....	10
4.9 Close.....	10
4.10 Get Version	10
5. OS Support	11
6. How to Import the Driver.....	11
6.1 e ² studio	11

1. Outline of Software Driver

The CPG (Clock Pulse Generator) driver controls the CPU clock, image processing clock, internal bus clock, and both peripheral clocks.

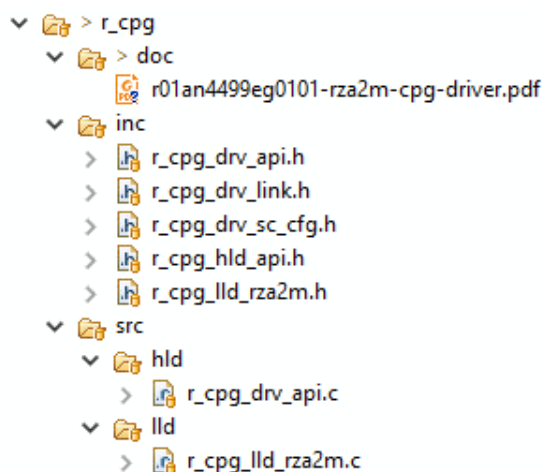
2. Description of the Software Driver

The key features of the driver include:

- Configures the main clock including the PLL and pre-PLL driver
- Sets each configurable sub-clock
- Sets inputs for all input-configurable clocks
- Configuration of external clock pins

2.1 Structure

The CPG driver is split into two parts: the High Layer Driver (HLD) and the Low Layer Driver (LLD). The HLD includes platform independent features of the driver, implemented via the STDIO standard functions. The LLD includes all the hardware specific functions.



2.2 Description of each file

Each file's description can be seen in the following table.

Filename	Usage	Description
Application-Facing Driver API		
r_cpg_drv_api.h	Application	The only API header file to include in application code
High Layer Driver (HLD) Source		
r_cpg_hld_prv.h	Private (HLD only)	Private header file intended ONLY for use in High Layer Driver (HLD) source. NOT for application or Low Layer Driver (LLD) use
r_cpg_drv_api.c	Private (HLD only)	High Layer Driver (HLD) source code enabling the driver API functions
r_cpg_hld_prv.c	Private (HLD only)	High Layer Driver (HLD) private source code enabling the functionality of the driver, abstracted from the low level access
High Layer to Low Level API		
r_cpg_lld_xxxx.h	Private (HLD/LLD only)	Low Layer Driver (LLD) header file (where "xxxx" is a device and board-specific identification). Intended ONLY to provide access for High Layer Driver (HLD) to required Low Layer Driver functions (LLD). Not for use in application, not to define any device specific enumerations or structures
r_cpg_lld_cfg_xxxx.h	Private (HLD/LLD only)	Low Layer Driver (LLD) header file (where "xxxx" is a device and board-specific identification). Intended for definitions of device specific settings (in the form of enumerations and structures). No LLD functions to be defined in this file
Abstraction Link between High and Low Layer Drivers (HLD/LLD Link)		
r_cpg_drv_link.h	Private (HLD/LLD only)	Header file intended as an abstraction between low and high layer. This header will include the device specific configuration file "r_cpg_lld_xxxx.h"
r_cpg_device_cfg.h	Should be included in "r_cpg_drv_api.h"	Header file intended as an abstraction between low and high layer. This header will include the device specific configuration file "r_cpg_lld_cfg_xxxx.h"
Low Layer Driver (LLD) Source		
r_cpg_lld_xxxx.c	Private (LLD only)	(Where "xxxx" is a device and board specific identification). Provides the definitions for the Low Layer Driver interface.
Smart Configurator		
r_cpg_drv_sc_cfg.h	Private (HLD/LLD only)	This file is intended to be used by Smart Configurator to pass setup information to the driver. This is not for application use

2.3 Driver API

The driver can be either used through STDIO or through direct access. It is recommended not to mix both access methods.

The API functions can be seen in the table below:

Return Type	Function	Description	Arguments	Return
int_t	cpg_hld_open (<i>st_stream_ptr_t</i> p_stream)	Driver initialisation interface is mapped to open function called directly using the <i>st_r_driver_t</i> CPG driver handle <i>g_cpg_driver</i> : i.e. g_cpg_driver.open()	[in] p_stream driver handle	>0: the handle to the driver DRV_ERROR Open failed
void	cpg_hld_close (<i>st_stream_ptr_t</i> p_stream)	Driver close interface is mapped to close function. Called directly using the <i>st_r_driver_t</i> CPG driver structure <i>g_cpg_driver</i> : i.e. g_cpg_driver.close()	[in] p_stream driver handle	None
int_t	cpg_hld_control (<i>st_stream_ptr_t</i> p_stream, <i>uint32_t</i> ctl_code, <i>void *</i> p_ctl_struct)	Driver control interface function. Maps to ANSI library low level control function. Called directly using the <i>st_r_driver_t</i> CPG driver structure <i>g_cpg_driver</i> : i.e. g_cpg_driver.control()	[in] p_stream driver handle. [in] ctl_code the type of control function to use. [in/out] p_ctl_struct Required parameter is dependent upon the control function.	DRV_SUCCESS Operation succeeded DRV_ERROR Operation failed
int_t	cpg_get_version (<i>st_stream_ptr_t</i> p_stream, <i>st_ver_info_ptr_t</i> p_ver_info)	Driver get_version interface function. Maps to extended non-ANSI library low level get_version function. Called directly using the <i>st_r_driver_t</i> CPG driver structure <i>g_cpg_driver</i> : i.e. g_cpg_driver.get_version()	[in] p_stream Handle to the (pre-opened) channel. [out] p_ver_info Pointer to a version information structure.	DRV_SUCCESS Operation succeeded

These High Layer functions can be accessed either executed directly or through STDIO.

3. Accessing the Driver

3.1 STDIO

The Driver API can be accessed through the ANSI 'C' library <stdio.h>. The following table details the operation of each function:

Operation	Return	Function Details
open	gs_stdio_handle, unique handle to driver	open(DEVICE_IDENTIFIER "cpg", O_RDWR);
close	DRV_SUCCESS successful operation, or driver specific error	close(gs_stdio_handle);
read	DRV_ERROR (read is not implemented in this STB driver)	read(gs_stdio_handle, buffer, buffer_length)
write	DRV_ERROR (write is not implemented in this STB driver)	write(gs_stdio_handle, buffer, data_length)
control	DRV_SUCCESS control was process, or driver specific error	control(gs_stdio_handle, CTRL, &struct);
get_version	DRV_SUCCESS drv_info was updated, or DRV_ERROR drv_info was not updated	get_version(DEVICE_IDENTIFIER "cpg", &drv_info);

3.2 Direct

The following table shows the available direct functions.

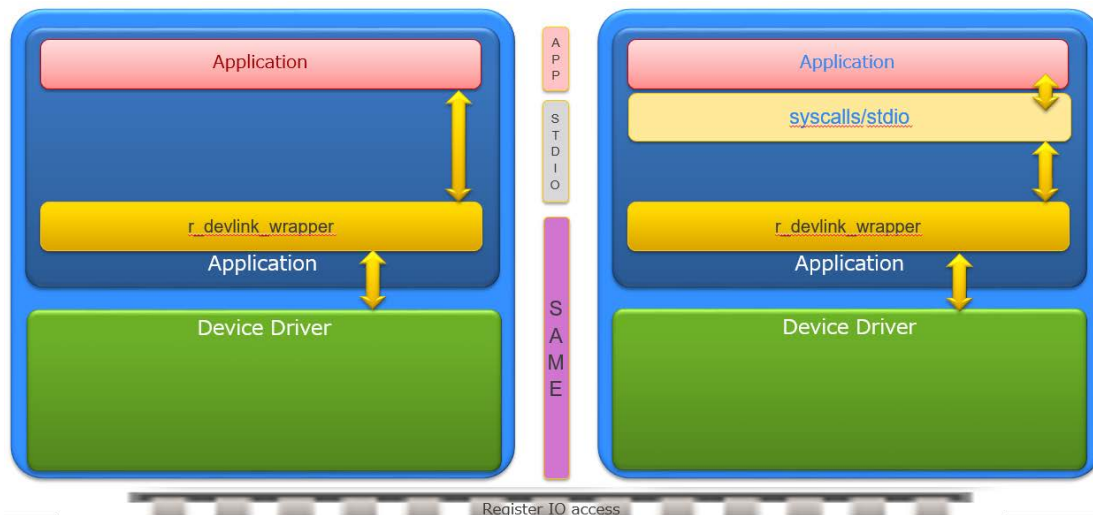
Operation	Return	Function details
open	gs_direct_handle unique handle to driver	direct_open("cpg", 0);
close	DRV_SUCCESS successful operation, or driver specific error	direct_close(gs_direct_handle);
read	DRV_ERROR (read is not implemented in this CPG driver)	direct_read(gs_direct_handle, buff, data_length);
write	DRV_ERROR (write not implemented in this CPG driver)	direct_write(gs_direct_handle, buff, data_length);
control	DRV_SUCCESS control was processed, or driver specific error	direct_control(gs_direct_handle, CTRL, &struct);
get_version	DRV_SUCCESS drv_info was updated, or DRV_ERROR drv_info was not updated	direct_get_version("cpg", &drv_info);

3.3 Comparison

The diagram below illustrates the difference between the direct and ANSI STDIO methods.

Direct

ANSI STDIO



4. Example of Use

This section gives simple examples for opening the driver, setting crystal frequency, setting the main clock, setting a sub clock, setting a sub clock source, setting an external clock, closing the driver, and finally getting the driver version.

4.1 Open

```
int_t gs_cpg_handle;
char_t *drv_name = "\\\\.\\cpg";

/* Note that the text "\\\\.\\\" in the drive name signifies to the STDIO
interface that the handle is to a peripheral and is not an access to a
standard file-based structure */

gs_cpg_handle = open(drv_name, O_RDWR);
```

4.2 Control – Set Crystal Frequency

```
int_t result;
float64_t xtal_frequency = 20000;

result = control(gs_cpg_handle, CTL_CPG_SET_XTAL_KHZ,
                (void *) &xtal_frequency);
```

4.3 Control – Set Main Clock

```
st_r_drv_cpg_set_main_t main_clk;

main_clk.main_clk_frequency_khz = 1056000;
main_clk.clk_src = CPG_CLOCK_SOURCE_PLL;
result = control(gs_cpg_handle, CTL_CPG_SET_MAIN_CLK, (void *) &main_clk);
```

4.4 Control – Set Sub Clock

```
st_r_drv_cpg_set_sub_t sub_clk;

sub_clk.clk_sub_src = CPG_SUB_CLOCK_ICLK;
sub_clk.sub_clk_frequency_khz = 100000;
result = control(gs_cpg_handle, CTL_CPG_SET_SUB_CLK, (void *) &sub_clk);
```

4.5 Control – Set Clock Source

```
st_r_drv_cpg_set_src_t clk_source;

clk_source.clk_sub_selection = CPG_SUB_CLOCK_HYPERBUS;
clk_source.clk_src_option = CPG_SUB_CLOCK_P1CLK_IN;
result = control(gs_cpg_handle, CTL_CPG_SET_CLK_SRC, (void *) &clk_source);
```

4.6 Control – Set External Clock

```
st_r_drv_cpg_ext_clk_t ext_clock;

ext_clock.clk_ext = CPG_CKIO_INVALID_UNSTBLE_NORM_ON_STDBY_DEEP_HIZ;
result = control(gs_cpg_handle, CTL_CPG_SET_EXT_CLK, (void *) &ext_clock);
```

4.7 Write

The stdio write() function is not supported by the CPG device driver.

4.8 Read

The stdio read() function is not supported by the CPG device driver.

4.9 Close

```
close(gs_cpg_handle);
```

4.10 Get Version

```
st_ver_info_t info;  
result = get_version(gs_cpg_handle, &info);
```

5. OS Support

This driver supports any OS through using the OS abstraction module. For more details about the abstraction module please refer to the OS abstraction module application note.

6. How to Import the Driver

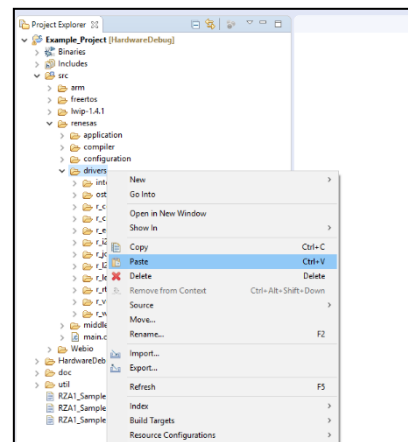
This section describes how to import the driver into your project. Generally, there are two steps in any IDE:

- 1) Copy the driver to the location in the source tree that you require for your project.
- 2) Add the include path of the driver to the compiler.

6.1 e² studio

To import the driver into your project please follow the instructions below.

- 1) In Windows Explorer, right-click on the `r_cpg` folder, and click **Copy**.
- 2) In e² studio Project Explorer view, select the folder where you wish the driver project to be located; right-click and click **Paste**.
- 3) Right-click on the parent project folder (in this case 'Example_Project') and click **Properties ...**
- 4) In 'C/C++ Build → Settings → Cross ARM Compiler → Includes', add the include folder of the newly added driver, e.g. `'${ProjDirPath}\src\renesas\drivers\r_cpg\inc'`



Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Sep.19.18	All	Created document.
1.01	May.10.19	All	Removed LLD details.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

Notice

1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
2. Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
4. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
5. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.

"Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.

"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.

Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.

6. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
7. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
8. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
9. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
10. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
11. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.

(Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.

(Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Rev.4.0-1 November 2017)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Trademarks

All trademarks and registered trademarks are the property of their respective owners.

Contact information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:
www.renesas.com/contact/.